



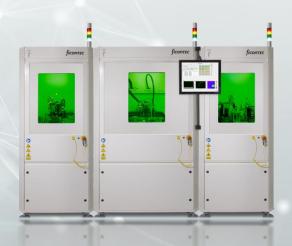
# EPIC Online Technology Meeting on Co-packaged Optics for Hyperscale Datacenters

PHOTONICS AUTOMATED ASSEMBLY AND TESTING

FROM FAB
LAB TO FAB

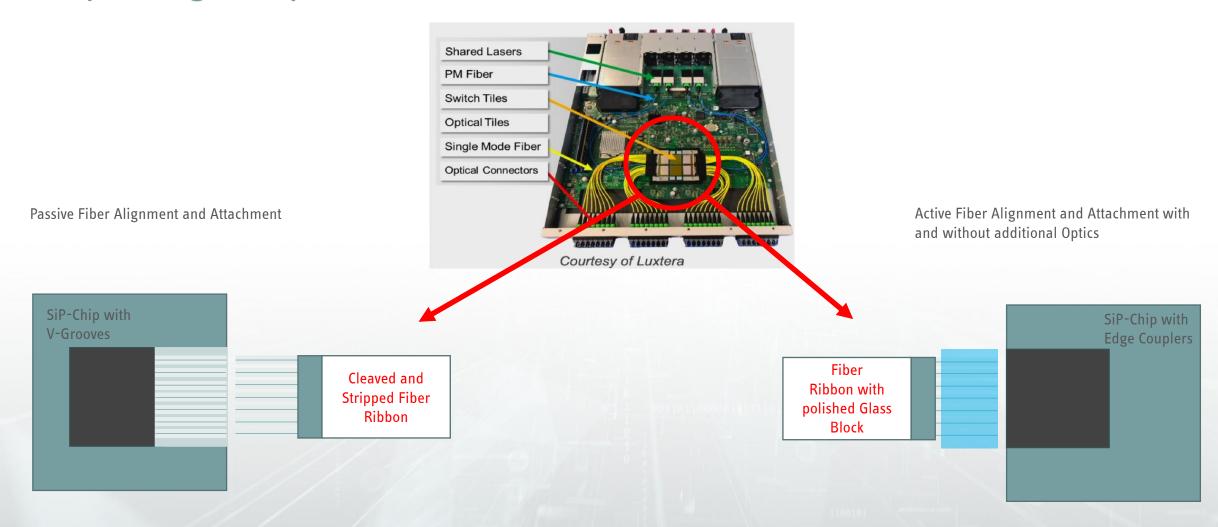
ficontec

Moritz Seyfried





#### Co-packaged Optics Switch Architecture



Source: https://community.cadence.com/cadence\_blogs\_8/b/breakfast-bytes/posts/the-photonics-summit-2019



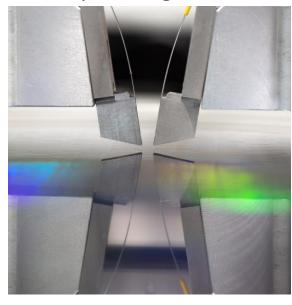
#### Electo-optical wafer level testing



Wafer table



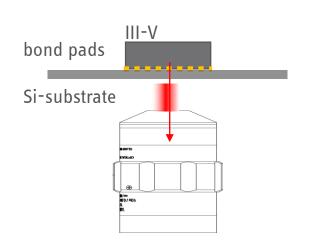
Optical alignment

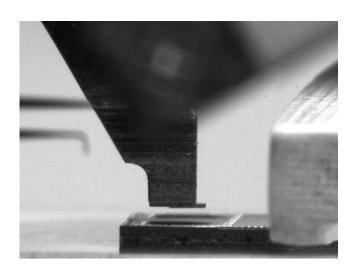


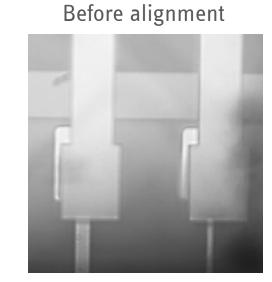
Electro-optical wafer level tester for verification of PIC functionality

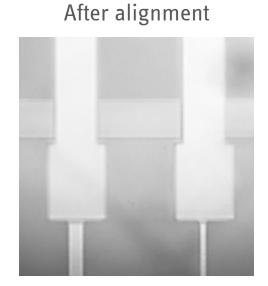


#### IR enabled passive laser to PIC attach

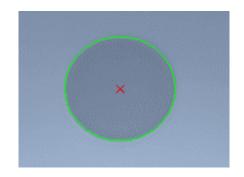








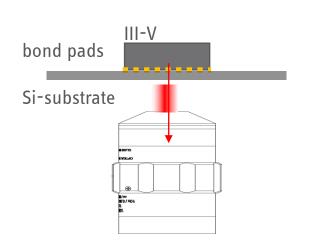


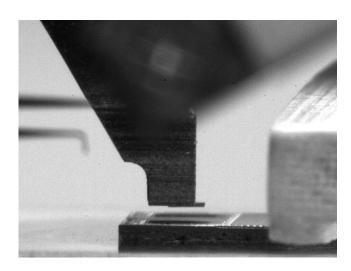


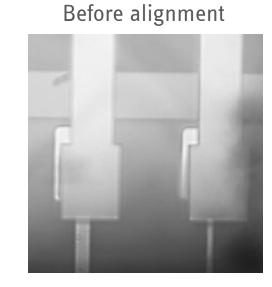
Accuracy of die tracking  $\sigma$  (x/y) = 0.07  $\mu$ m / 0.06  $\mu$ m

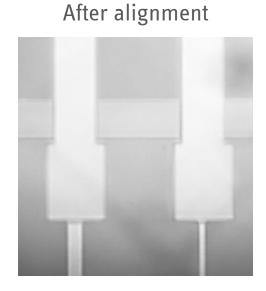


#### IR enabled passive laser to PIC attach





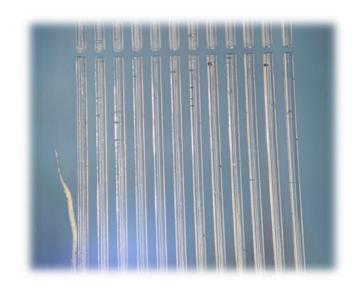






Can be combined with localized through-silicon laser soldering





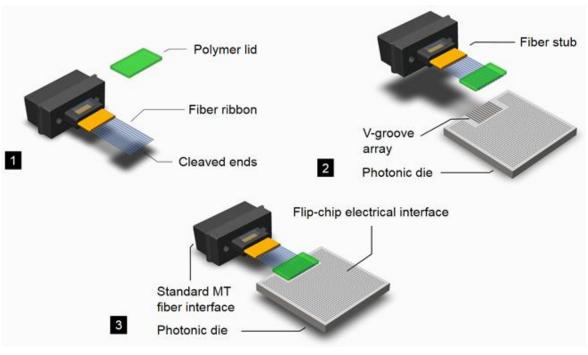
### **FIBERLINE**

## **Automated Fiber Ribbon Insertion**

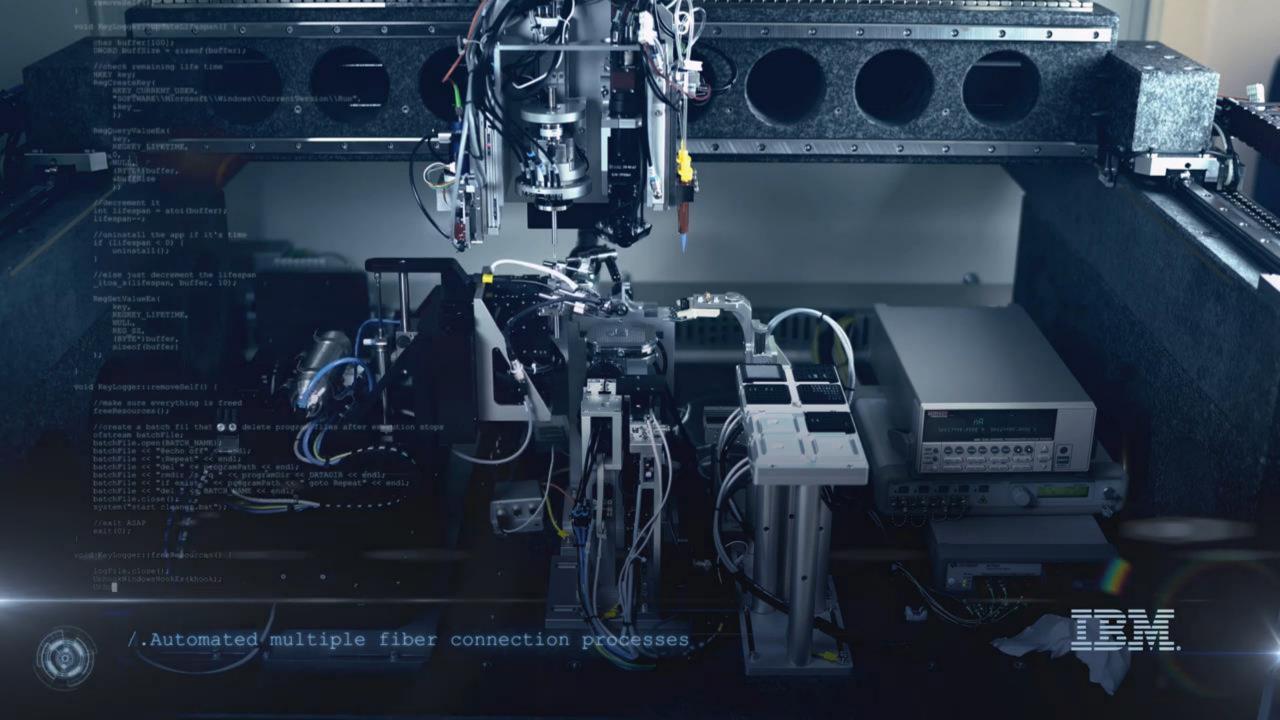


#### Passive fiber to v-groove assembly



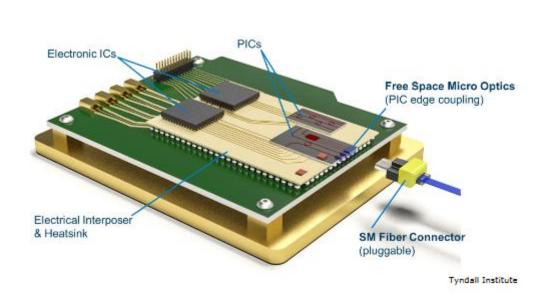








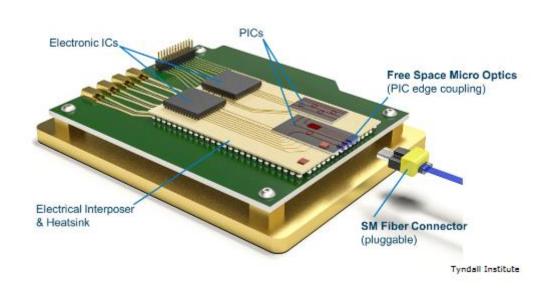
#### Micro lens for pluggable connectors







#### Micro lens for pluggable connectors





Aligned fiber array and lens



#### Multiple individual solutions available











Fiber prep



#### High throughput concepts



Assembly line



#### High throughput concepts + ficonEDGE

#### **KPI** tracking



#### AI /ML for process optimization





Assembly line



## Thank you!